

1

2

3

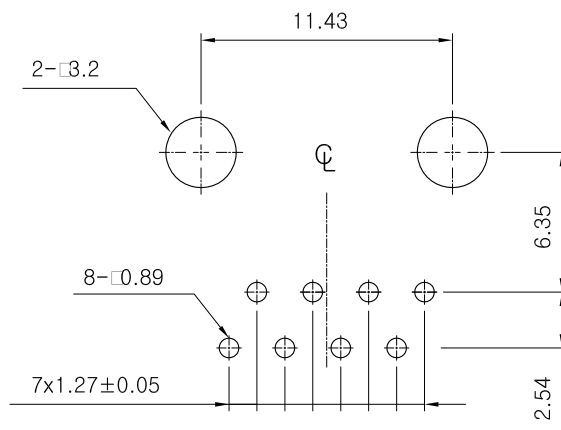
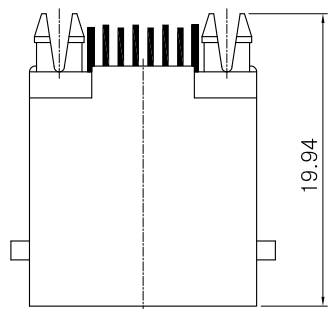
4

MARK

DESCRIPTION

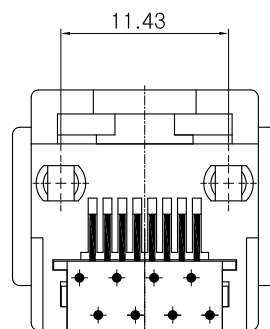
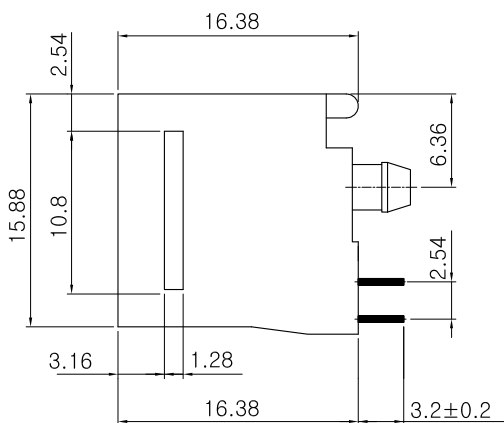
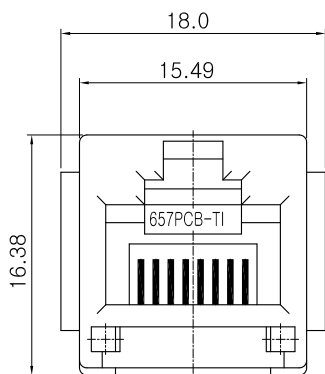
A

A

PCB LAY-OUT

B

B



C

C

NOTE

1. GOLD PLATING THICKNESS IS 3, 6, 15, 30, 50M-IN
2. FCC TEST CONDITIONS ARE SATISFIED
3. MATERIAL IS UL APPROVED
4. OTHERWISE TOLERANCE .0±0.2 , .00±0.1
5. BE ABLE TO USE 2 , 4 , 6 OR 8PIN

D

D

NO	部 番 PART NO.	名 稱 TITLE	材 料 MATERIAL	規 格 SPECIFICATION	處 理 TREATMENT	備 考 REMARK
			三角法 THIRD ANGLE PROJECTION	單 位 UNIT mm INCH	尺 度 SCALE 1 / 1	提出先 USER
			承認 APPROVAL	檢 圖 CHECK	設 計 DESIGN	圖 名 TITLE
						圖 番 Drawing No.
MARK	DATE	APPR	CHECK	DESIGN		

DEK개발 007모 A4(06. 11. 21)

**대은전자주식회사**

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